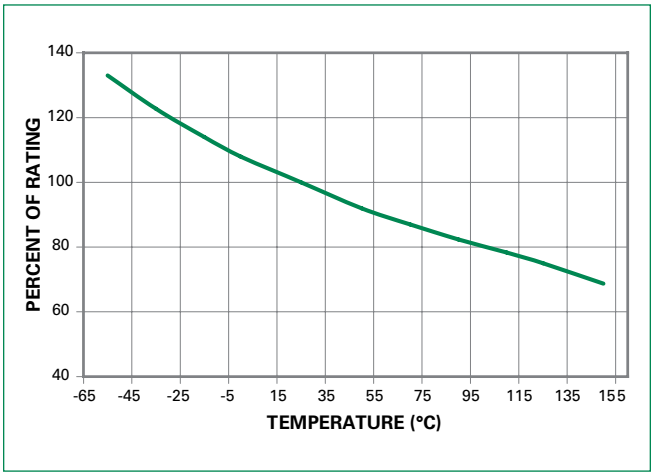
Temperature Re-rating Curve



Note:

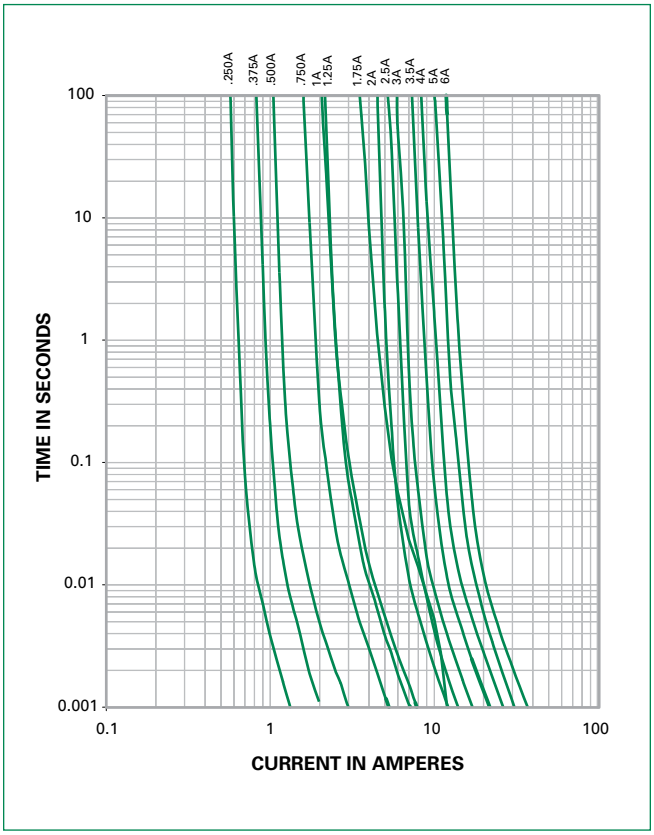
1. Re-rating depicted in this curve is in addition to the standard re-rating of 20% for continuous operation.

Example:

For continuous operation at 75 degrees celsius, the fuse should be rerated as follows:

$I = (0.80)(0.85)I_{RAT} = (0.68)I_{RAT}$

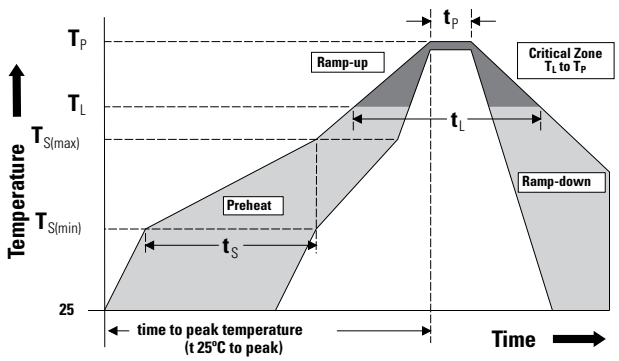
Average Time Current Curves



Soldering Parameters

Reflow Condition		Pb – free assembly
Pre Heat	**- Temperature Min ($T_{s(min)}$)**	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 seconds
Average Ramp-up Rate (Liquidus Temp (T_L) to peak)		3°C/second max.
$T_{S(max)}$ to T_L - Ramp-up Rate		5°C/second max.
Reflow	**- Temperature (T_L) (Liquidus)**	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		$260^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		10 – 30 seconds
Ramp-down Rate		6°C/second max.
Time 25°C to peak Temperature (T_P)		8 minutes max.
Do not exceed		260°C

Wave Soldering	260°C, 10 seconds max.



Revised: 10/11/19

Surface Mount Fuses

Ceramic Fuse > 438A Series

Product Characteristics

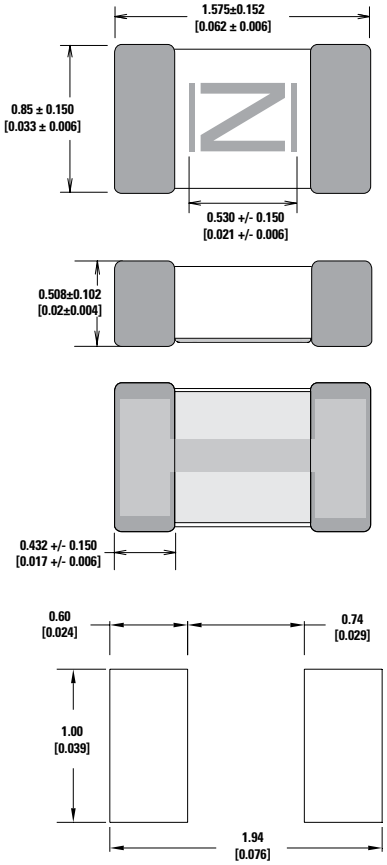
Materials	**Body:** Advanced Ceramic **Terminations:** Ag/Ni/Sn (100% Lead-free) **Element Cover Coating:** Lead-free Glass
Moisture Sensitivity Level	IPC/JEDEC J-STD-020, Level 1
Solderability	IPC/EIC/JEDEC J-STD-002, Condition C
Humidity Test	MIL-STD-202, Method 103, Conditions D
Resistance to Solder Heat	MIL-STD-202, Method 210, Condition B
Moisture Resistance	MIL-STD-202, Method 106

Thermal Shock	MIL-STD-202, Method 107, Condition B
Mechanical Shock	MIL-STD-202, Method 213, Condition A
Vibration	MIL-STD-202, Method 201
Vibration, High Frequency	MIL-STD-202, Method 204, Condition D
Dissolution of Metallization	IPC/EIC/JEDEC J-STD-002, Condition D
Terminal Strength	IEC 60127-4

High Temperature Storage	MIL-STD-202 Method 108 with exemptions
Thermal Shock Test	JESD22 Method JA-104, Test Conditions B and N
Biased Humidity	MIL-STD-202 Method 103, 85°C/85% RH with 10% operating power for 1000 hrs
Operational Life	MIL-STD-202 Method 108, Test Condition D
Resistance To Solvents	MIL-STD-202 Method 215
Mechanical Shock	MIL-STD-202 Method 213, Test Condition C

High Frequency Vibration	MIL-STD-202, Method 204
Resistance To Soldering Heat	MIL-STD-202 Method 210, Test Condition B
Solderability	JESD22-B102E Method 1
Terminal Strength For SMD	AEC Q200-006
Board Flex	AEC Q200-005
Electrical Characterization	3 Temperature Electrical Characterization

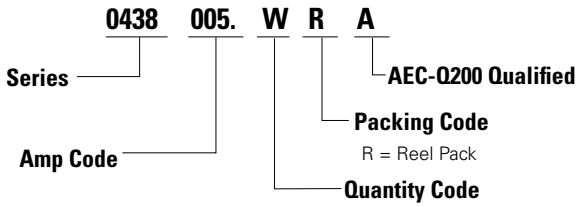
Dimensions



Part Marking System

Amp Code	Marking Code
.250	D
.375	E
.500	F
.750	G
001.	H
1.25	J
1.75	L
002.	N
02.5	O
003.	P
03.5	R
004.	S
005.	T
006.	U

Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
8mm Tape and Reel	EIA-481, IEC 60286, Part 3	3000	WR

Revised: 10/11/19